Texas Instruments

Bill of Materials

TI DESIGNS

TIDA-3D-PRINTERPACK

Item	Qty	Reference/Designator	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	Eagle Footprint
1	4	C11, C23, C29, C35	10nF	CAP CER 10000PF 50V 20% X7R 0805	Samsung	CL21B103MBANNNC		C0805
2	4	C12, C24, C30, C36	.47uF	CAP CER 0.47UF 50V 10% X7R 0805	Samsung	CL21B474KBFNNNE		C0805
3	11	C13, C14, C25, C26, C31, C32, C37, C38, C2, C42, C44	0.1uF	CAP CER 0.1UF 50V Y5V 0805	Samsung	CL21F104ZBCNNNC		C0805
4	4	C15, C27, C33, C39	0.1uF	CAP CER 0.1UF 50V 10% X7R 0603	Samsung	CL10B104KB8SFNC		C0603
5	4	C16, C28, C34, C40	4.7uF	CAP CER 4.7UF 50V 10% X5R 0805	Samsung	CL21A475KBQNNNE		C0805
6	4	C4,C7,C9,C10	47uF	CAP ALUM 47UF 50V 20% RADIAL	Panasonic	ECA-1HM470		E2,5-6
7	1	C6	100uF	CAP ALUM 100UF 50V 20% RADIAL	Nichicon	UVR1H101MPD		E3,5-8
8	3	C41, C5, C8	10uF	CAP CER 10UF 35V Y5V 1206	Taiyo Yuden	GMK316F106ZL-T		C1206
9	1	C43	0.33u	CAP CER 0.33UF 50V 10% X7R 0805	Samsung	CL21B334KBFNNNE		C0805
10	2	D1, D2	1N4004	DIODE GEN PURPOSE 400V 1A DO41	Comchip	1N4004-G		DO41-10
11	5	E0-MOT1, JP1, X-MOT1, Y-MOT1, Z-MOT1		PIN HEADER	FCI	68002-404HLF		4PIN-HEADER
12	1	F1	MFR500	FUSE PTC RESETTABLE 5A HOLD	Bourns	MF-R500		MFR500
13	1	F2	MFR1100	POLYSWITCH PTC RESET 11A HLD T/R	TE Connectivity	RGEF1100-2		MFR1100
14	1	LED1	RED	LED SUPER RED CLEAR 0805 SMD	Lite-On	LTST-C170KRKT		CHIP-LED0805
15	3	LED2, LED3, LED4	GREEN	LED GREEN CLEAR THIN 0805 SMD	Lite-On	LTST-C171GKT		CHIP-LED0805
16	1	MICROSD	SD-502702-003	CONN MICRO SD R/A PUSH-PUSH SMD	Molex	5027020891		SD-502702-003
17	2	MSP430F5529LAUNCHPADXL	MSP430F5529XL	F5529 launchpad headers	Samsung	SSW-110-23-F-D		10x2PIN-HEADER
18	3	Q1, Q2, Q3	CSD18534KCS	MOSFET N-CH 60V 100A TO220-3	TI	CSD18534KCS		TO220BV
19	2	R1, R7	4.7K	RES 4.7K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ472		R0805
20	1	R12	1K	RES 1K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ102		R0805
21	3	R13, R14, R15	10r	RES 10 OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ100		R0805
22	4	R16, R29, R37, R45	1.5k	RES 1.5K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ152		R0805
23	8	R18, R30, R32, R38, R40, R41, R46, R48	10k	RES 10K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ103		R0805
24	7	R2, R4, R9, R20, R31, R39, R47	100k	RES 100K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ104		R0805
25	3	R23, R24, R25	1.8K	RES 1.8K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ182		R0805
26	4	R3, R5, R26, R42	10k	TRIMMER 10K OHM 0.1W SMD	Bourns	TC33X-2-103E		SM-42/43A
27	1	R49	47k	RES 47K OHM .4W 5% 0805 SMD	Rohm	ESR10EZPJ473		R0805
28	8	R6, R10, R17, R27, R28, R36, R43, R44	0.10r	RES .100 OHM 1W 1% 2010 SMD	TT Electronics	LRC-LR2010LF-01-R100F		R2512
29	1	RESET	SPST-NO	SWITCH TACTILE SPST-NO 0.02A 15V	Panasonic	EVQ-11L05R		PBTH
30	12	SJ1, SJ2, SJ3, SJ4, SJ5, SJ6, SJ7, SJ8, SJ9, SJ10, SJ11, SJ12		SMD solder JUMPER				SJ
31	4	U$1, U$4, U$5, U$6	DRV8825PWP	IC MOTOR DRIVER PAR 28HTSSOP	TI	DRV8825PWP		TSSOP-28
32	1	U$2	282837-6	TERM BLOCK PCB 6POS 5.0MM GREEN	Phoenix	1935200		282837-6
33	1	UA78M33	UA78M33	IC REG LDO 3.3V 0.5A SOT223	TI	UA78M33CDCYR		SOT223
34	6	X+, X-, Y+, Y-, Z+, Z-		PIN HEADER	FCI	68001-203HLF		3PIN-HEADER
35	1	X4	MSTBA4	TERM BLOCK PCB 4POS 5.0MM GREEN	Phoenix	1935187		MSTBA4

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